

FEATURES

- Fast Switching Device (TRR <6.0 nS)
- Power Dissipation of 250mW
- High Stability and High Reliability
- Low reverse leakage



SOD-323

MECHANICAL DATA

- SOD-323 Small Outline Plastic Package
- Polarity: Color band denotes cathode end
- Mounting Position: Any

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS (T_A=25°C)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V _R	75	V
Peak Reverse Voltage	V _{RM}	85	V
Power Dissipation	P _D	250	mW
Average Rectified Current	I _O	250	mA
Thermal Resistance from Junction to Ambient	R _{θJA}	500	°C/W
Peak Forward Surge Current @tp=1us; T _A =25°C	I _{FSM}	2.0	A
Operating junction temperature	T _J	150	°C
Storage temperature range	T _{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS($T_A=25^{\circ}\text{C}$)

Parameter	Test Condition	Symbol	Min.	Max.	Unit
Reverse Voltage	$I_R = 10\mu\text{A}$	$V_{(BR)}$	75		V
Reverse Leakage Current	$V_R = 25\text{V}$	I_R		30	nA
	$V_R = 75\text{V}$			1.0	μA
Forward Voltage	$I_F = 1.0\text{mA}$	V_F		0.715	V
	$I_F = 10\text{mA}$			0.855	V
	$I_F = 50\text{mA}$			1.00	V
	$I_F = 150\text{mA}$			1.25	V
Reverse Recovery Time	$I_F = I_R = 10\text{mA}$	T_{RR}		6.0	nS
	$R_L = 100\Omega$				
	$I_{RR} = 0.1I_R$				
Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$	C_T		2.0	pF

CHARACTERISTIC CURVES

Fig 1. Forward Characteristics

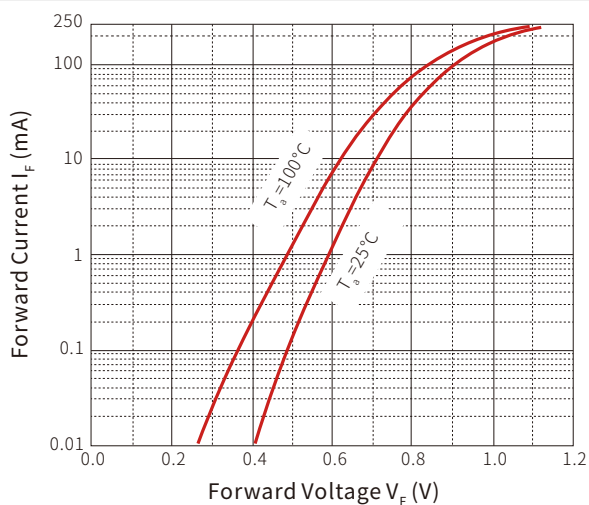


Fig 2. Reverse Characteristics

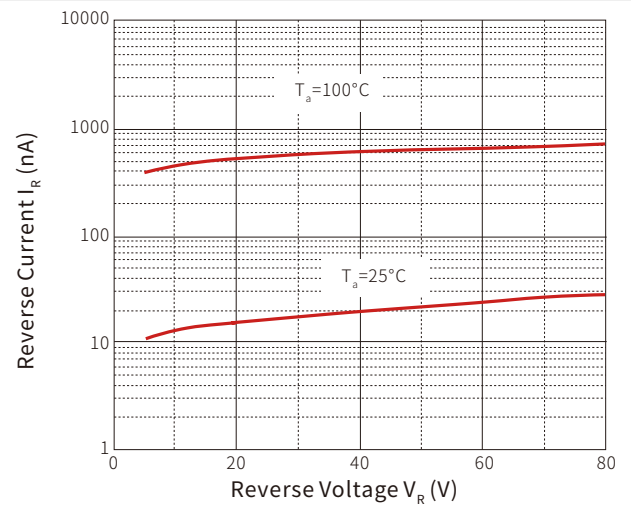
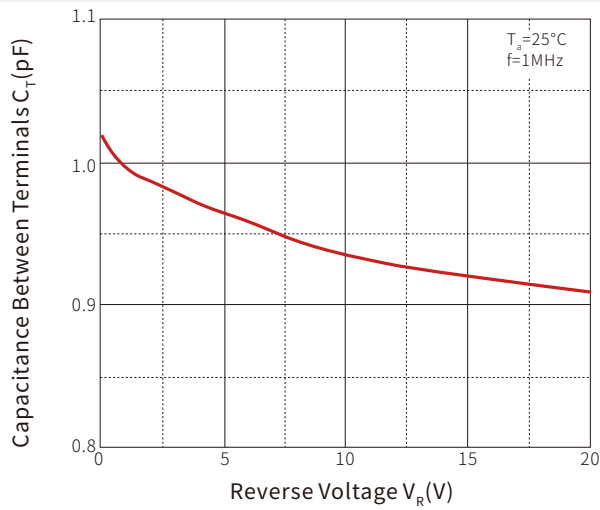
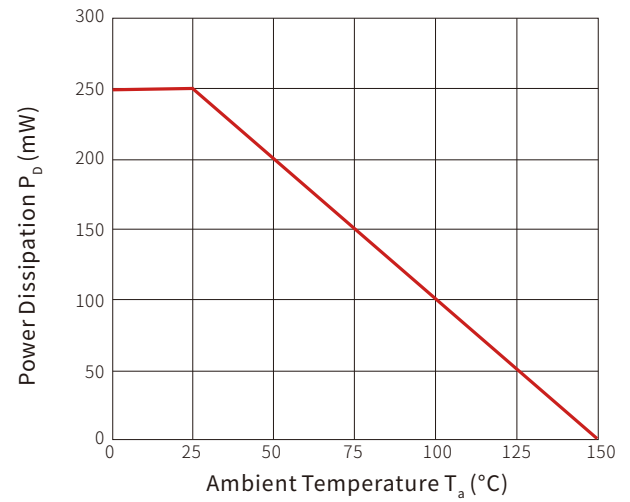
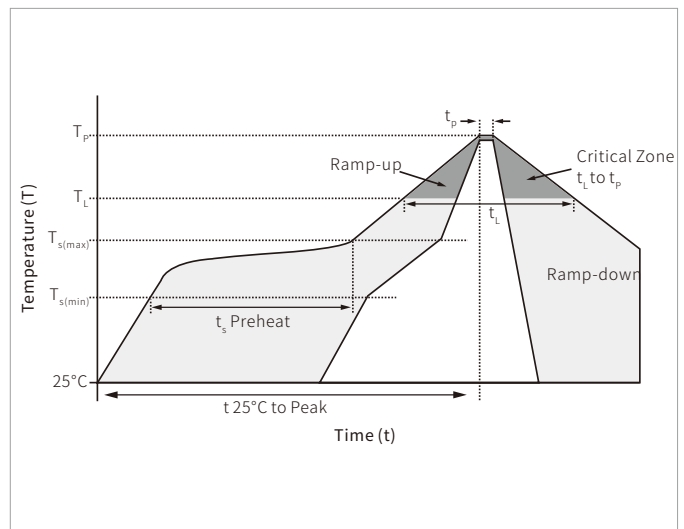


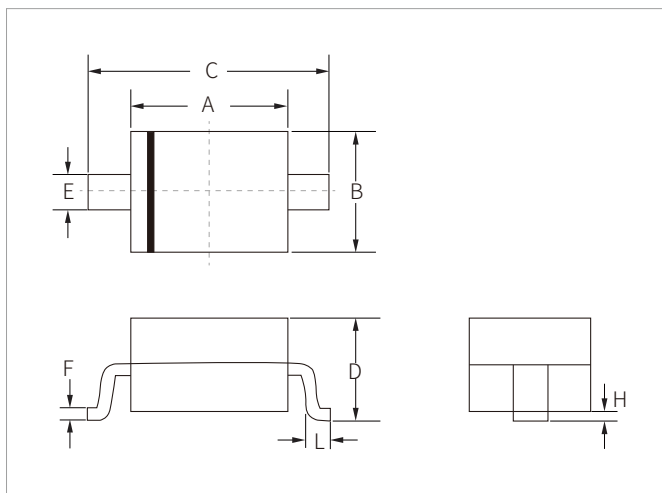
Fig 3. Capacitance Characteristics

Fig 4. Power Derating Curve


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(\min)}$)	150°C
	Temperature Max ($T_{s(\max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(\max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

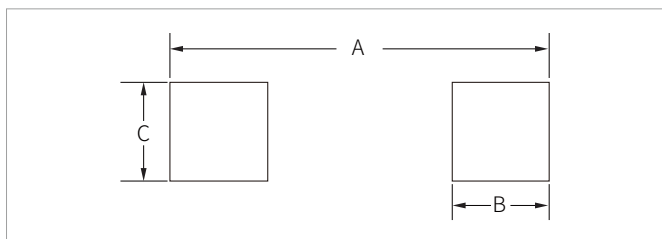


SOD-323 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.60	1.90	0.063	0.075
B	1.15	1.45	0.045	0.057
C	2.35	2.75	0.093	0.108
D	0.80	1.10	0.031	0.043
E	0.25	0.40	0.010	0.016
F	0.10	0.20	0.004	0.008
H	-	0.10	-	0.004
L	0.20	0.40	0.008	0.016

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.87	3.12	0.113	0.123
B	0.66	0.91	0.026	0.036
C	0.66	0.91	0.026	0.036

ORDERING INFORMATION

Part Number	Marking	Component Package	QTY/Reel	Reel Size
BAS16WS	T4	SOD-323	3000PCS	7"

Headquarters

No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service

Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support

Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

By QR Code

Website



Wechat

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